B. Patterning 분과

Room B
1F / 105호

2015년 2월 11일(수) 09:00-10:30
[WB1-B] Patterning
좌장: 유원종 (성균관대학교), 정지원 (인하대학교)

WB1-B-1	**09:00-09:15**	**Deep Contact Hole Patterning for 3D NAND Flash** 구본왕, 김종훈, 김영식 SK Hynix Inc. 미래기술 연구원 PHOTO Technology Team
WB1-B-2	**09:15-09:30**	**EUV Multilayer Defect Compensation in Computational Lithography** 김상곤 한양대학교
WB1-B-3	**09:30-09:45**	**Negative Tone Development Process Window according to Pattern Size** Doyoun Kim, Seyoung Oh, Hyoungsoon Yune, Daejin Park, Woosung Moon, Hyunjo Yang, and Donggyu Yim Research & Development Division, SK Hynix Inc.
WB1-B-5	**10:00-10:15**	**Overlay Metrology In Cell Area with Design based Metrology** Gyoyeon Jo[1], Jungchan Kim[1], Sunkeun Ji[1], Chanha Park[1], Minwoo Park[1], Hyunwoo Kang[1], Hyunjo Yang[1], Donggyu Yim[1], Masahiro Yamamoto[2], Kotaro Maruyama[2], and Byungjun Park[1] [1]Research & Development Division, SK Hynix Inc., Korea, [2]NGR Inc. Japan
WB1-B-6	**10:15-10:30**	**Study and Control of Reticle Heating Contribution to Total Overlay Error Budget for Sub-20-nm Devices** Byong-Seog Lee, Honggoo Lee, Sangjun Han, Wontaik Kwon, and Myoungsoo Kim R&D Div., SK Hynix Inc. Semiconductor Inc.